

Features

- Integrated Phase-Locked Loop (PLL)
- Low Jitter, High Accuracy Outputs
- VCXO with Analog Adjust
- 3.3 V Operation
- Compatible with MK3727 (-1, -4)
- Application compatibility for a wide variety of Designs

CY241V08A-01, -04 Logic Block Diagram

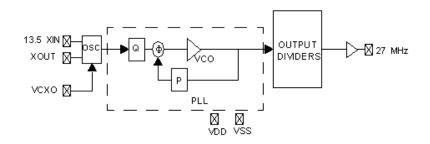
- Enables Design compatibility
- Lower Drive Strength settings (CY241V08A–04)

Benefits

- Digital VCXO control
- Second source for existing designs
- Highest performance PLL tailored for multimedia applications
- Meets critical timing requirements in complex system designs

Functional Description

For a complete list of related documentation, click here.



Selector Guide

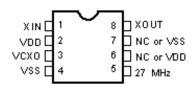
Part Number	Outputs	Input Frequency Range	Output Frequencies	VCXO Control Curve	Other Features
CY241V08A-01	1	13.5 MHz pullable crystal input according to Cypress specification	1 copy of 27 MHz	linear	Compatible with MK3727
CY241V08A-04		13.5 MHz pullable crystal input according to Cypress specification	1 copy of 27 MHz		Same as CY241V08A-01 except lower drive strength settings



Pin Configurations

Figure 1. 8-pin SOIC pinout

CY241V08A-01, -04



Pin Descriptions

Name	Pin Number	Description
XIN	1	Reference crystal input
VDD	2	Voltage supply
VCXO	3	Input analog control for VCXO
VSS	4	Ground
27 MHz	5	27 MHz clock output
NC/VDD	6	No connect or voltage supply
NC/VSS	7	No connect or ground
XOUT	8	Reference crystal output



Absolute Maximum Conditions

Exceeding maximum ratings may shorten the useful life of the device. User guidelines are not tested.

Supply Voltage (V _{DD}))–0.5 to +7.0 V
DC Input Voltage	-0.5 V to V _{DD} + 0.5 V

. –55 °C to +125 °C
–40 °C to +125 °C
> 10 years
350 mW
> 2000 V

Pullable Crystal Specifications

Parameter ^[1]	Description	Comments	Min	Тур	Мах	Unit
F _{NOM}	Nominal crystal frequency	Parallel resonance, fundamental mode, AT cut	-	13.5	_	MHz
C _{LNOM}	Nominal load capacitance		_	14	-	pF
R ₁	Equivalent series resistance (ESR)	Fundamental mode	-	-	25	Ω
R ₃ /R ₁	Ratio of third overtone mode ESR to fundamental mode ESR	Ratio used because typical R ₁ values are much less than the maximum spec	3	-	_	-
DL	Crystal drive level	No external series resistor assumed	150	-	-	μW
F _{3SEPHI}	Third overtone separation from 3 × F _{NOM}	High side	300	-	-	ppm
F _{3SEPLO}	Third overtone separation from 3 × F _{NOM}	Low side	-	-	-150	ppm
C ₀	Crystal shunt capacitance		-	-	7	pF
C ₀ /C ₁	Ratio of shunt to motional capacitance		180	-	250	-
C ₁	Crystal motional capacitance		14.4	18	21.6	fF

Recommended Operating Conditions

Parameter	Description		Тур	Max	Unit
V _{DD}	Operating Voltage		3.3	3.465	V
T _A	Ambient Temperature	0	-	70	°C
C _{LOAD}	Maximum Load Capacitance	-	-	15	pF
t _{PU}	Power up time for all VDD pins to reach minimum specified voltage (power ramps must be monotonic)	0.05	_	500	ms

Note
1. Crystals that meet this specification include: Ecliptek ECX-5788-13.500M, Siward XTL001050A-13.5-14-400, Raltron A-13.500-14-CL, PDI HA13500XFSA14XC.



DC Electrical Specifications

Parameter	Name	Description	Min	Тур	Max	Unit
I _{OH}	Output HIGH Current	$V_{OH} = V_{DD} - 0.5 \text{ V}, \text{ V}_{DD} = 3.3 \text{ V}$	12	24	-	mA
I _{OL}	Output LOW Current	V _{OL} = 0.5 V, V _{DD} = 3.3 V	12	24	-	mA
C _{IN}	Input Capacitance	Except XIN, XOUT pins	-	-	7	pF
V _{VCXO}	VCXO Input Range		0	-	V _{DD}	V
f _{ΔXO} [2]	VCXO Pullability Range	Low Side	-	-	-115	ppm
		High Side	115	-	-	ppm
I _{VDD}	Supply Current		-	30	35	mA

Thermal Resistance

Parameter ^[3]	Description	Test Conditions	8-pin SOIC	Unit
Θ_{JA}	(junction to ambient)	Test conditions follow standard test methods and procedures for measuring thermal impedance, according		°C/W
Θ^{JC}	Thermal resistance (junction to case)	to EIA/JESD51.	53	°C/W

AC Electrical Specifications

(V_{DD} = 3.3 V)

Parameter ^[4]	Name	Description	Min	Тур	Max	Unit
DC	Output Duty Cycle	Duty Cycle is defined in Figure 3, 50% of V_{DD}	45	50	55	%
ER _{OR}	Rising Edge Rate -01	Output Clock Edge Rate, Measured from 20% to 80% of V _{DD} , C _{LOAD} = 15 pF See Figure 4.	0.8	1.4	_	V/ns
ER _{OF}	Falling Edge Rate -01	Output Clock Edge Rate, Measured from 80% to 20% of V _{DD} , C _{LOAD} = 15 pF, See Figure 4.	0.8	1.4	_	V/ns
ER _{OR}	Rising Edge Rate -04	Output Clock Edge Rate, Measured from 20% to 80% of V _{DD} , C _{LOAD} = 15 pF, See Figure 4.	0.7	1.1	-	V/ns
ER _{OF}	Falling Edge Rate -04	Output Clock Edge Rate, Measured from 80% to 20% of V _{DD} , C _{LOAD} = 15 pF, See Figure 4.	0.7	1.1	-	V/ns
t ₉	Clock Jitter	Peak-to-peak period jitter	-	-	100	ps
t ₁₀	PLL Lock Time		-	-	3	ms

Notes

3. Tested initially and after any design or process change that may affect these parameters.

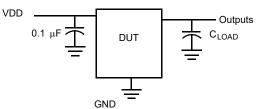
4. Not 100% tested.

^{2. -115/+115} ppm assumes 2.5 pF of additional board level load capacitance. This range will be shifted down with more board capacitance or shifted up with less board capacitance.

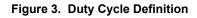


Test and Measurement Setup





Voltage and Timing Definitions



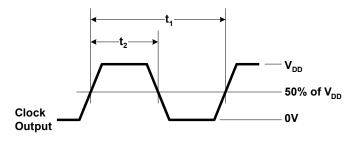
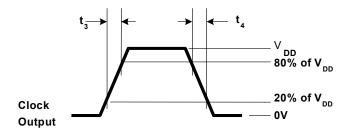


Figure 4. ER = $(0.6 \text{ x V}_{DD})/t_3$, EF = $(0.6 \text{ x V}_{DD})/t_4$





Ordering Information

Ordering Code	Package Type	Operating Range	Operating Voltage	Features
Pure Sn		-		
CY241V8ASXC-1S	8-pin SOIC	Commercial	3.3 V	Linear VCXO control curve
Ordering Code Definitions $\frac{CY}{1} \xrightarrow{241V8A} \xrightarrow{S} \xrightarrow{X} \xrightarrow{C}$		(= blank or T lank = Tube; T opecific Configur emperature Gra c = Commercial	ration Code: XX	K = 01 or 1

Pb-free

Package Type: S = 8-pin SOIC Base Part Number

Company ID: CY = Cypress

Not Recommended for New Designs

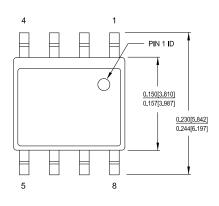


Package Diagrams

Figure 5. 8-pin SOIC (150 Mils) S0815/SZ815/SW815 Package Outline, 51-85066

- 1. DIMENSIONS IN INCHES[MM] MIN. MAX.
- 2. PIN 1 ID IS OPTIONAL, ROUND ON SINGLE LEADFRAME RECTANGULAR ON MATRIX LEADFRAME
- 3. REFERENCE JEDEC MS-012
- 4. PACKAGE WEIGHT 0.07gms

PART #		
S08.15	STANDARD PKG	
SZ08.15	LEAD FREE PKG	
SW8.15	LEAD FREE PKG	



0.010[0.254] X 45° 0.189[4.800] SEATING PLANE 0.196[4.978] 0.016[0.406] 0.061[1.549] 0.068[1.727] 0.004[0.100] \frown 0.050[1.270] BSC 0.0075[0.190] 0.004[0.100] 0.0098[0.249] 0°~8° 0.016[0.406] 0.0098[0.249] 0.035[0.889] 0.0138[0.350] 0.0192[0.487]

51-85066 *I



Acronyms

Acronym	Description
ESD	Electrostatic Discharge
ESR	Equivalent Series Resistance
PLL	Phase Locked Loop
SOIC	Small Outline Integrated Circuit
VCXO	Voltage Controlled Crystal Oscillator

Document Conventions

Units of Measure

Symbol	Unit of Measure		
°C	degree Celsius		
fF	femtofarad		
MHz	megahertz		
μF	microfarad		
μW	microwatt		
mA	milliampere		
ms	millisecond		
mW	milliwatt		
ns	nanosecond		
Ω	ohm		
%	percent		
pF	picofarad		
ppm	parts per million		
ps	picosecond		
V	volt		



Document History Page

Rev.	ECN No.	Submission Date	Description of Change
**	214069	03/26/2004	New data sheet.
*A	220404	04/22/2004	Minor Change: Post to external web.
*B	393122	08/22/2005	Updated Document Title to read as "CY241V08A-01,04/CY241V8A-01, MPEG Clock Generator with VCXO". Updated Ordering Information: Updated part numbers.
*C	414184	12/14/2005	Minor Change: Updated Benefits: Deleted unnecessary text.
*D	455059	04/21/2006	Updated Ordering Information: Updated part numbers. Updated to new template. Post to internal spec system.
*E	2759384	09/02/2009	Updated to new template. Post to external web.
*F	2897423	03/22/2010	Updated Ordering Information: Updated part numbers. Updated Package Diagrams: spec 51-85066 – Changed revision from *C to *D. Updated to new template. Completing Sunset Review.
*G	4009177	05/23/2013	Updated Ordering Information: No change in part numbers. Added Ordering Code Definitions. Updated Package Diagrams: spec 51-85066 – Changed revision from *D to *F. Added Acronyms and Units of Measure. Updated to new template. Completing Sunset Review.
*H	4580603	11/26/2014	Updated Functional Description: Added "For a complete list of related documentation, click here." at the end. Updated Ordering Information: Updated part numbers.
*	5267358	05/11/2016	Added Thermal Resistance. Updated Package Diagrams: spec 51-85066 – Changed revision from *F to *H. Updated to new template. Completing Sunset Review.
*J	6073305	02/16/2018	Updated Package Diagrams: spec 51-85066 – Changed revision from *H to *I. Updated to new template.
*K	6903402	06/22/2020	Added watermark "Not Recommended for New Designs" across the document. Updated to new template. Completing Sunset Review.



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